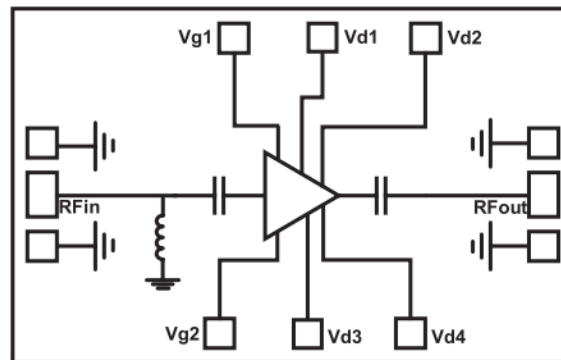


**Features**

- Frequency: 27.5-30GHz
- Gain: 19dB
- P1dB: +33dBm@26%
- OIP3: +39dBm
- Power Supply: 6V@0.9A
- Die Size : 2.9x 2.4 x 0.1 mm

**Functional Block Diagram**

**Typical Applications**

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

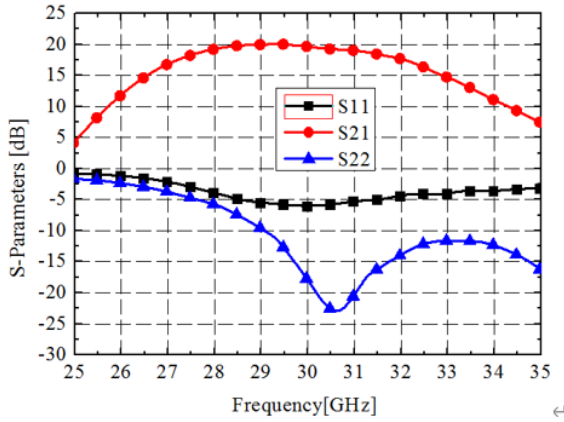
**Electrical Specifications**

TA = +25°C, Vd1 = Vd2 = +6V, Vg = -0.8V , Id1 + Id2 = 0.9A [1]

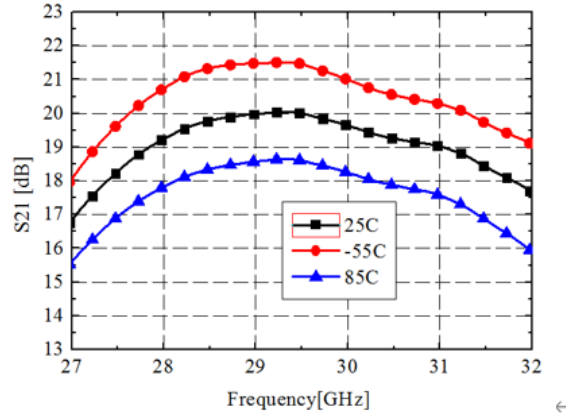
Parameters	Min.	Typ.	Max.	Units
Frequency	27.5-30			GHz
Gain	18.5	19	20	dB
Rate of gain change		0.022		dB/°C
P1dB	32.5	33	33.5	dBm
Psat	33	33.5		dBm
PAE	20	26		%
OIP3	38	39		dBm
Input Return Loss		5		dB
Output Return Loss		10		dB
Operating Current (@Vd = 6V)		0.9		A

[1] Adjust Vg from -1V~0V so that Id=0.9A

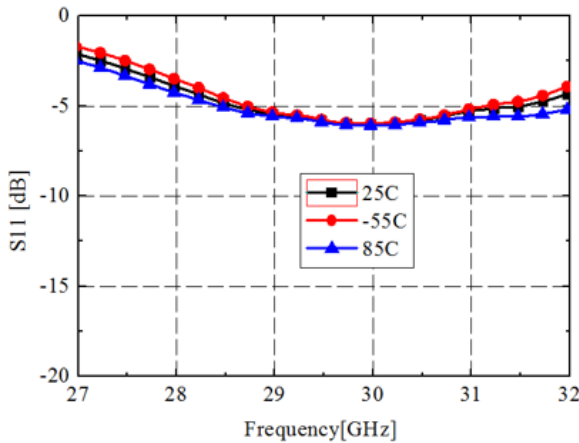
### Frequency Response



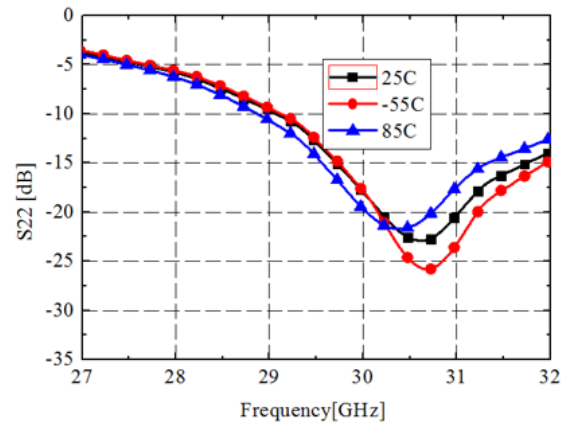
### Gain vs. Temperature



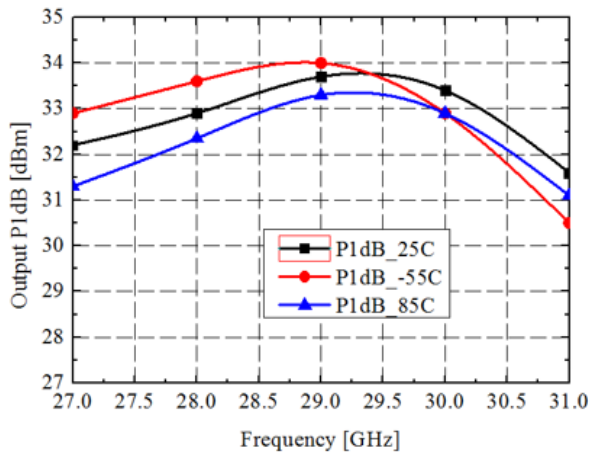
### Input Return Loss vs. Temperature



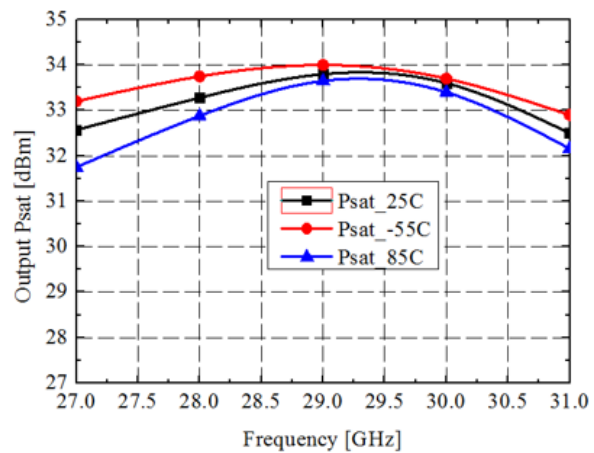
### Output Return Loss vs. Temperature



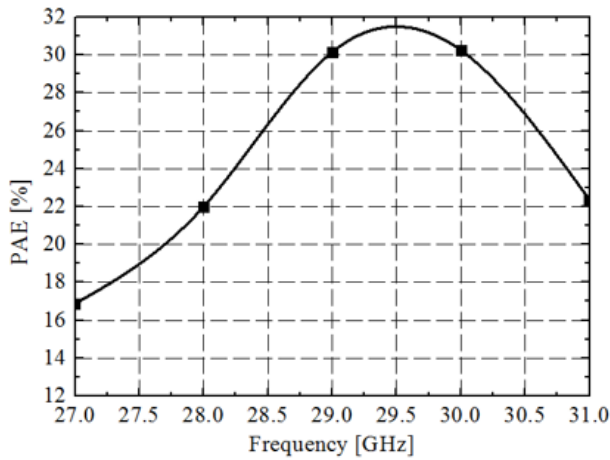
### P1dB vs. Temperature



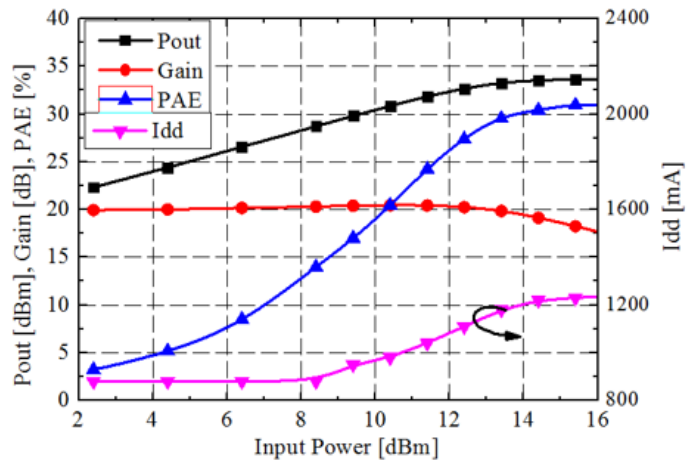
### Psat vs. Temperature



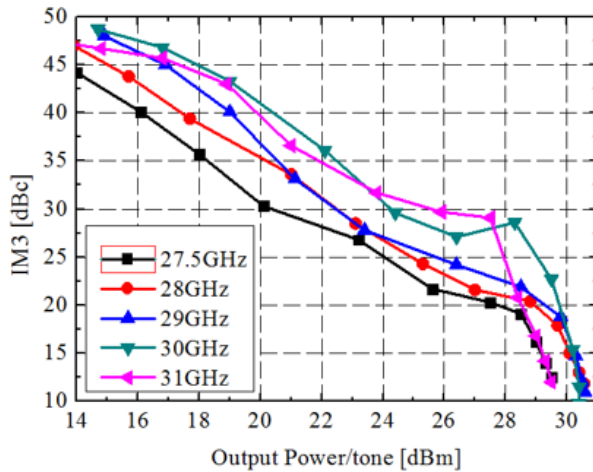
PAE@P1dB vs. Frequency



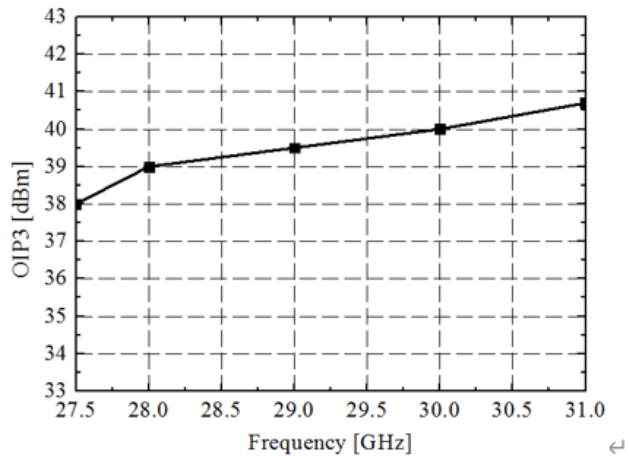
Gain, Output Power, Idd, PAE vs. Input Power @29GHz



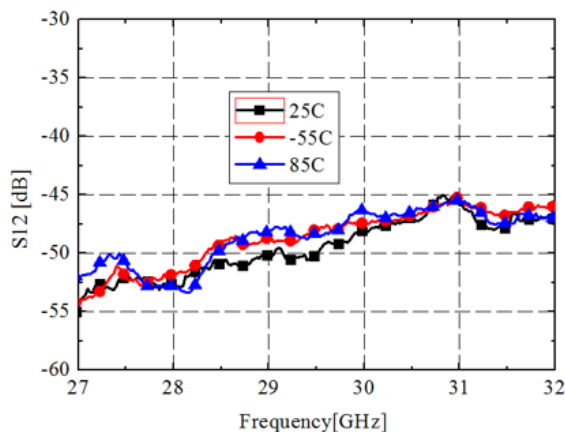
IMD3 vs. Output Power



OIP3 vs. Frequency (Pout/Tone = 28dBm)

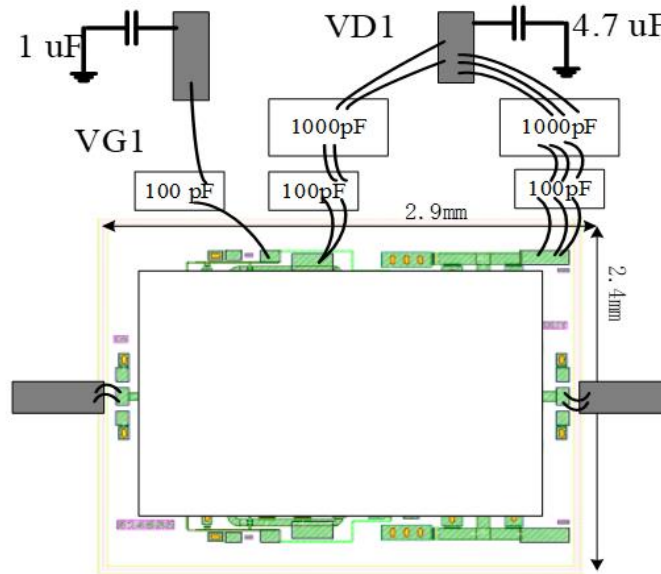


Reverse Isolation vs. Temperature





### Assembly Drawing (Bond testing)



\*Due to the symmetry of the chip, the bottom side of the chip can also be selected for bonding feeding.

#### Notes:

1. Die thickness: 100um
2. Typical bond pad is 100\*100  $\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

#### Maximum Ratings:

1. Drain Bias voltage: +6.5V
2. RF Input Power: +22dBm
3. Channel Temperature: 175°C
4. Thermal Resistance: 12°C/W
5. Operating temperature: -55°C to +85°C
6. Storage temperature: -65°C to +150°C